



Hardware Open Systems Technology (HOST)

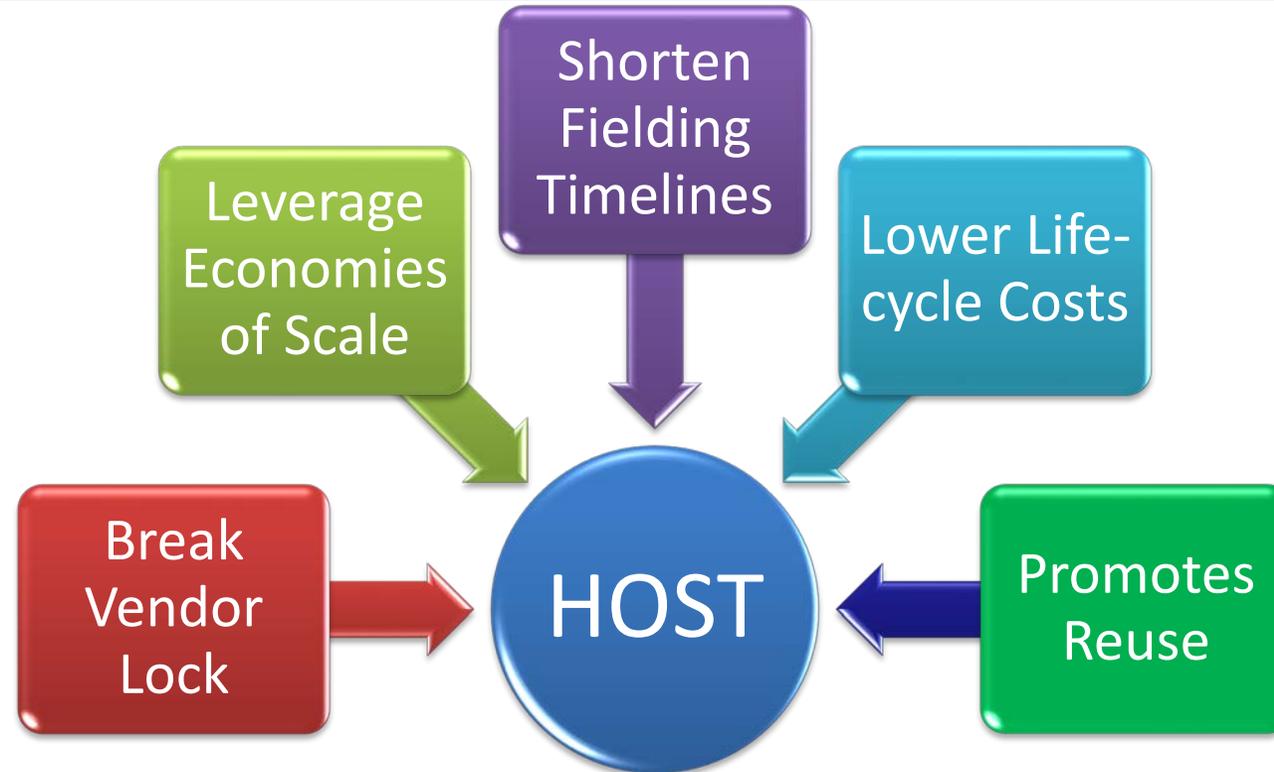
HARDWARE OPEN SYSTEMS TECHNOLOGIES

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NAVAIR PMA209**

HOST – A Key Pillar of NAVAIR's Open Architecture Approach

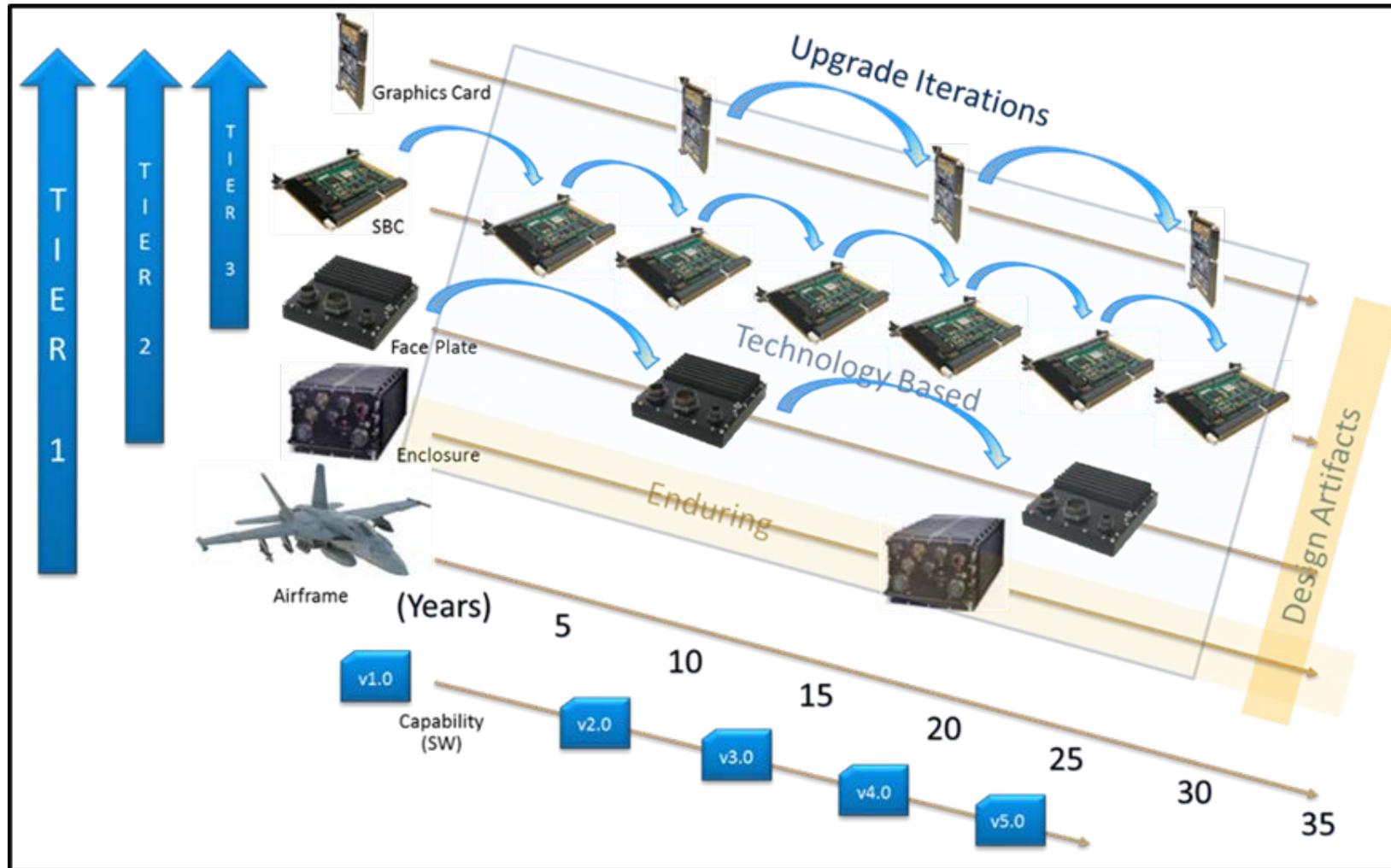


Key Goals



" Provides a framework for developing embedded computing systems for U.S. military platforms. HOST provides U.S. Government Acquisition, System Integrators, and Third Party HOST Component Vendors with an open, interoperable, upgradeable, and sustainable embedded system standard."

HOST Development Overview



HOST Benefits



Old Paradigm

Circuit Card Assembly

Custom Functionality
Defined by Integrator

Custom Set of Cards

Inter Card Jumpers
Complicates Wiring

New Paradigm

HOST Assembly

Standardized
Interfaces to Provide
Functionality

Standardized Set of
Cards

Utilizes Defined
Interfaces Over Back,
and Mid Plane

The HOST Standards



TIER I: CORE TENETS (Single Document)

Preserve HOST “openness” by establishing universal requirements that apply to all HOST components regardless of core technology

TIER II: CORE TECHNOLOGIES (Document for each core technology chosen)

Define platform agnostic technical requirements for core technologies (Examples are OpenVPX, PC104, and VME)

TIER III: COMPONENT SPECIFICATIONS (Many Documents)

These are component level documents that will guide H/W development to facilitate modular components, Tier III reuse, and upgradeability

Tier 1 HOST Components



- HOST Components
 - Enclosures, Transmission Components, External Interfaces and Modules

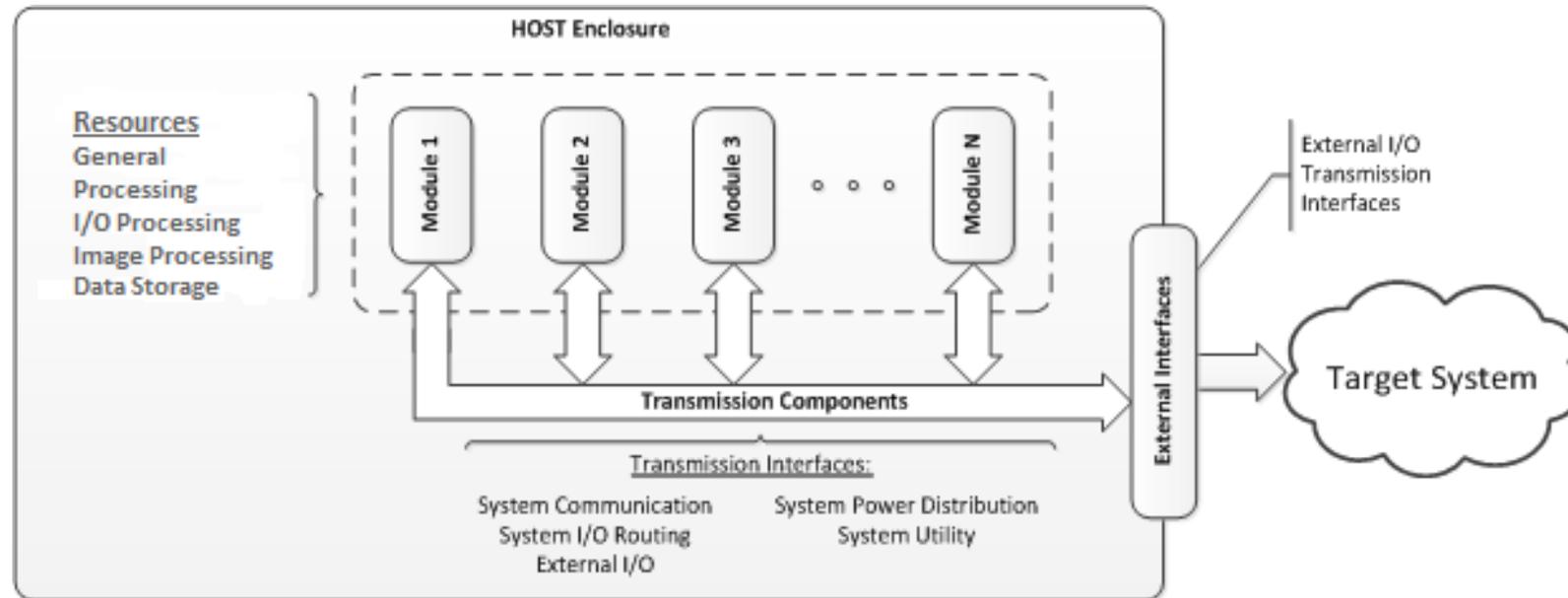
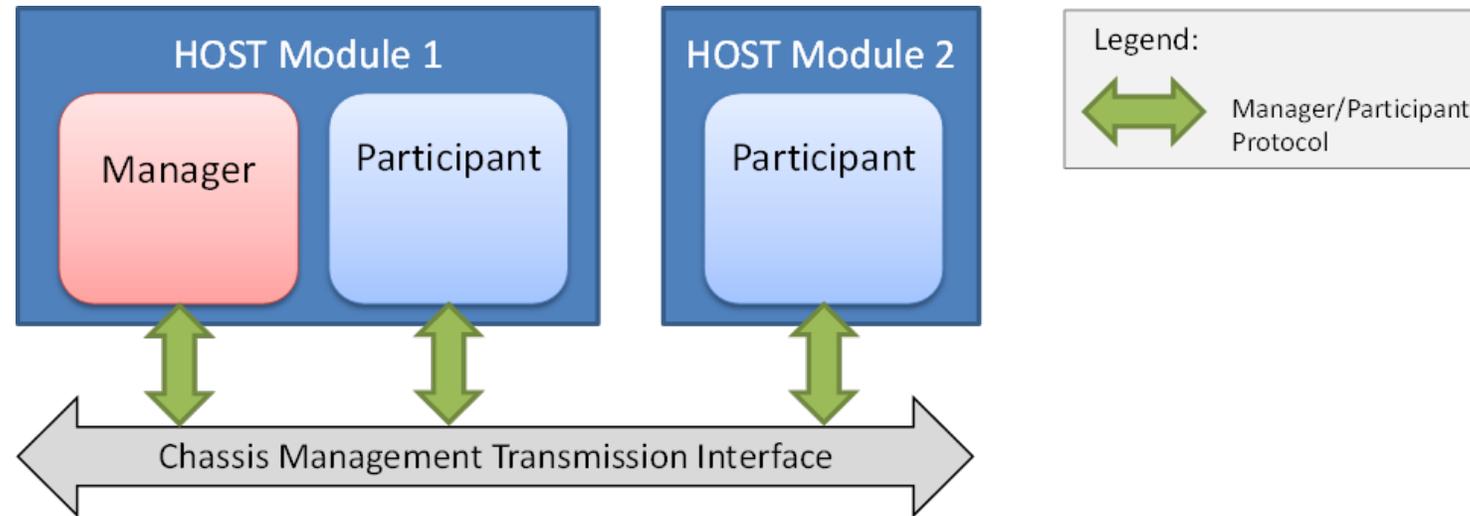


Figure 4-2 – Example HOST Component Categories

Tier 1 HOST-Management (HOST-MGMT)

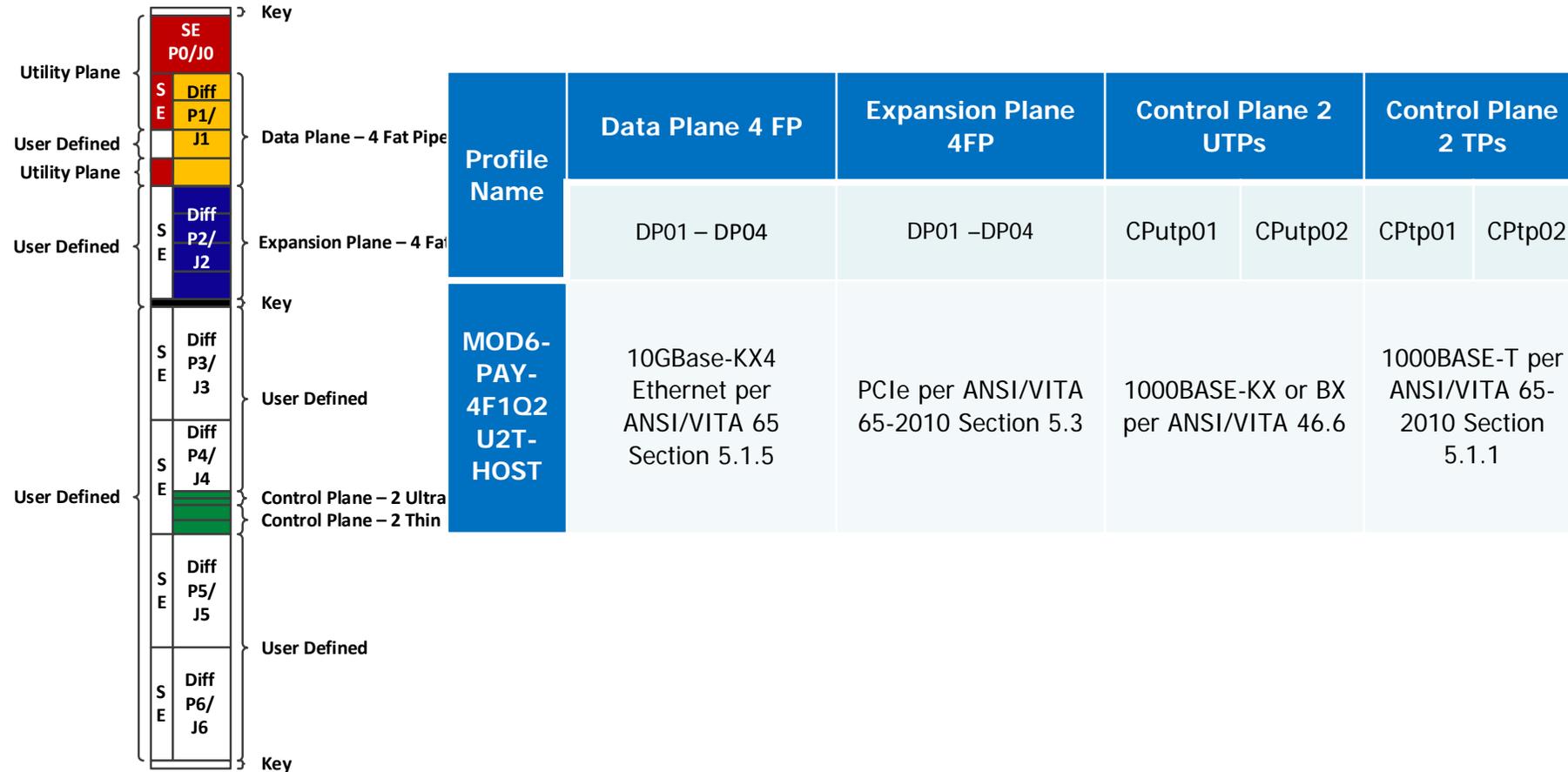


Autonomous subsystem that provides application independent hardware management and monitoring capabilities

**Logical control elements for HOST-MGMT representation
Managers (chassis-level) and Participants (module-level)**

**Manager/Participants Protocol (MPP) defines
standardized means of data exchange**

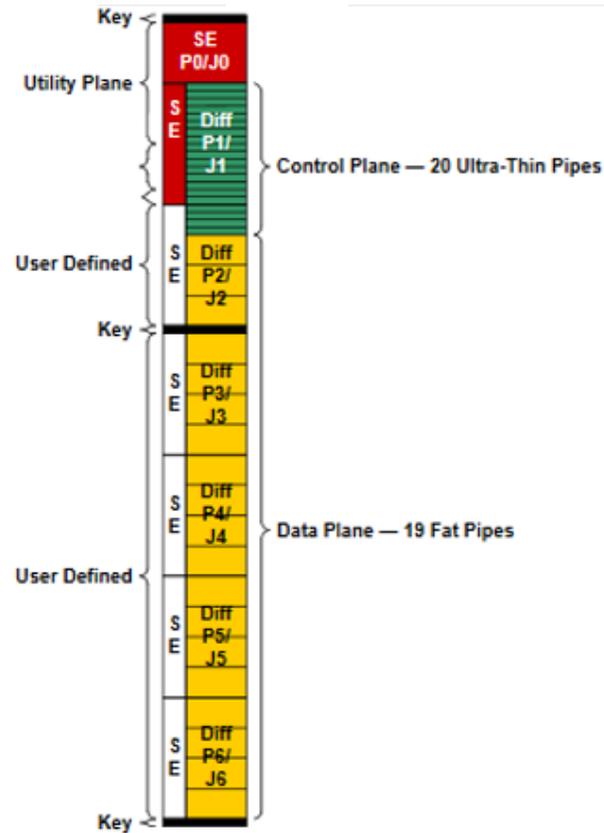
Tier 2 Payload Modules



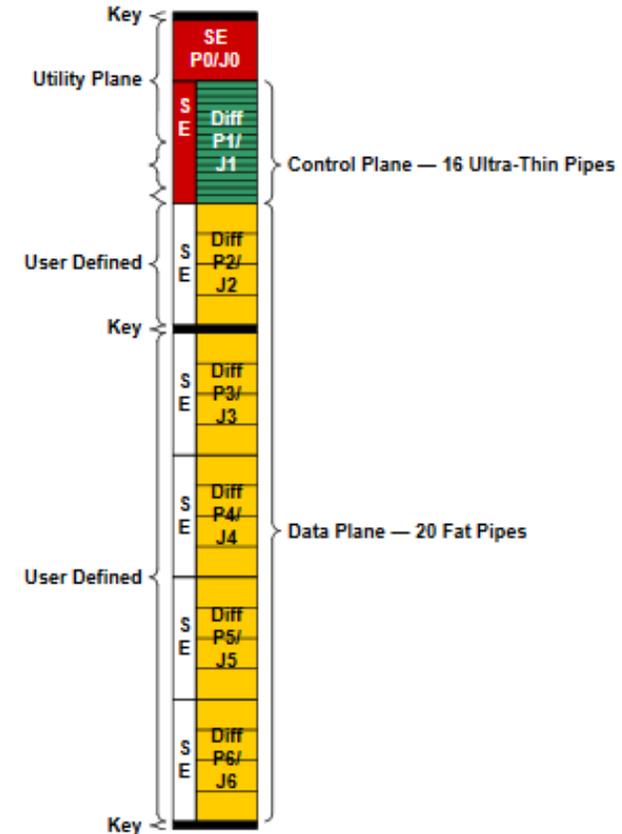
SLT6-PAY-4F1Q2U2T-HOST

T2-PER-0045: Payload Modules **may** implement 10GBASE-KR on the Control Plane UTPs.

Tier 2 Switch Modules



Profile 1



Profile 2

Tier 2 Payload Modules

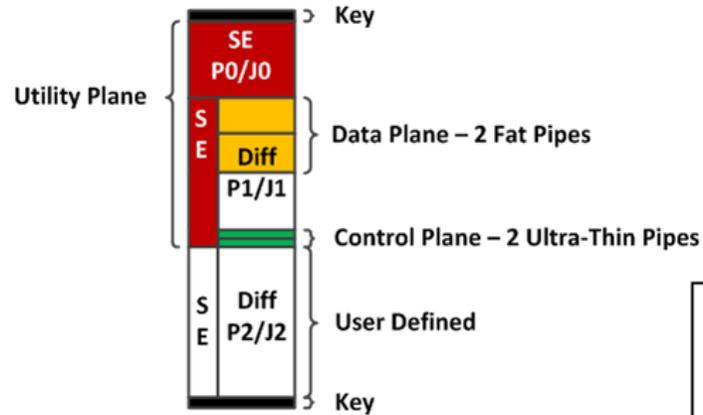
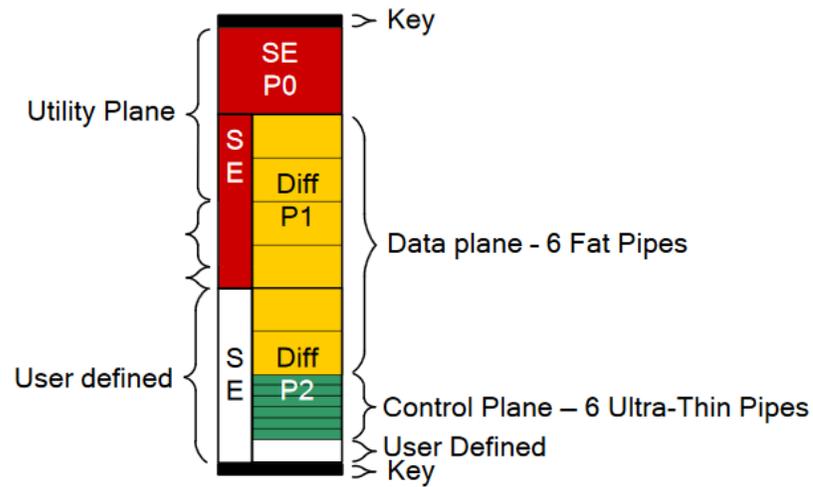


Figure 5-2 – HOST Payload Slot Profile, SLT3-PAY-2F2U-HOST

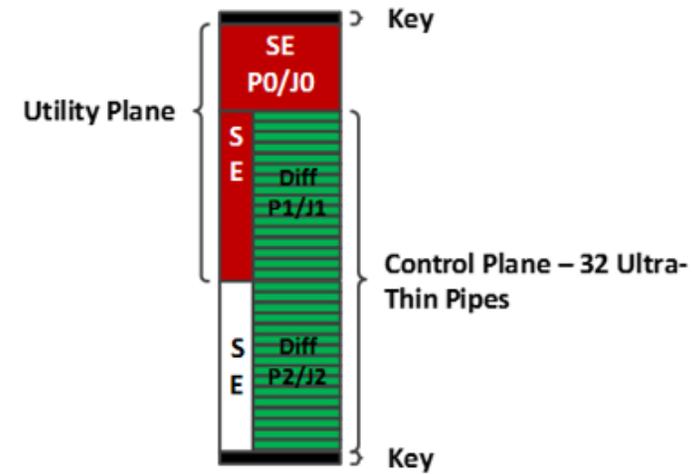
Profile Name	Data Plane 2 FP		Control Plane 2 UTPs	
	DP01	DP02	CPutp01	CPutp02
MOD3-2F2U-HOST	PCIe per ANSI/VITA 65-2010 Section 5.3		1000BASE-KX or BX per ANSI/VITA 46.6	

T2-PER-0045: Payload Modules **may** implement 10GBASE-KR on the Control Plane UTPs.

Tier 2 Switch Modules



Profile 1



Profile 2

Tier 2 Payload Modules



- Mezzanine Mapping
 - HOST calls out specific ANSI/VITA 46.9 I/O mapping for Payload Modules that have Mezzanine sites.
 - 46.9 calls out ways for Plug-In Modules to route I/O from their Mezzanine Sites to the backplane connector(i.e RT 2-R) wafers.

Conn	Wafer	Pin Fields
P3/P5	1	
	2	
	3	
	4	
	5	
	6	
	7	
	8	P64s
	9	P64s
	10	P64s
	11	
	12	
	13	
	14	
	15	X8d
	16	
P4/P6	1	
	2	
	3	X12d
	4	X12d
	5	X12d
	6	X12d
	7	X12d
	8	X8d
	9	
	10	X8d

Figure 5-1: 6U VPX Carrier Backplane Pin Field Summary
From VITA46.9

Conn	Wafer	Pin Fields	
P1	9		
	10		
	11	X12d	
	12		
	13		
	14		
	15		
	16		
	P2	1	
		2	
		3	
		4	
		5	
		6	
		7	
		8	
9		P64s	
10		P64s	
11		X8d	
12		X24s	
13		X8d	
14		X8d	
15		X8d	
16		X8d	

Figure 4-1: 3U VPX Carrier VITA 46.0 Connector Pin Field Summary
From VITA46.9

Questions

